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Variant: 001

Generated: 11/24/2017 10:52:03 AM

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TIDA-01613 REV E1 Bill of Materials



Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01613	Any	Printed Circuit Board	
2	C0	1	47uF	TPSA476K006R0800	AVX	CAP, TA, 47 μF, 6.3 V, +/- 10%, 0.8 ohm, SMD	3216-18
3	C1, C4	2	22uF	GRM31CR71A226KE15L	MuRata	CAP, CERM, 22 μF, 10 V, +/- 10%, X7R, 1206	1206
4	C2, C21	2	22uF	12103D226MAT2A	AVX	CAP, CERM, 22 μF, 25 V, +/- 20%, X5R, 1210	1210
5	C3, C8, C11,	9	0.33uF	GRM219R71H334KA88D	MuRata	CAP, CERM, 0.33 µF, 50 V, +/- 10%, X7R, 0805	0805
	C12, C13, C17,						
	C18, C20, C24						
6	C5	1	33pF	C0805C330J5GACTU	Kemet	CAP, CERM, 33 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
7	C6	1	470pF	08055A471FAT2A	AVX	CAP, CERM, 470 pF, 50 V, +/- 1%, C0G/NP0, 0805	0805
8	C7, C28	2	0.01uF	08055C103JAT2A	AVX	CAP, CERM, 0.01 µF, 50 V, +/- 5%, X7R, 0805	0805
9	C9	1	0.22uF	C2012X7R1H224K	TDK	CAP, CERM, 0.22 µF, 50 V, +/- 10%, X7R, 0805	0805
10	C10	1	68pF	GQM2195C1H680JB01D	MuRata	CAP, CERM, 68 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
11	C14, C19, C25	3	1uF	GRM21BR71H105KA12L	MuRata	CAP, CERM, 1 μF, 50 V, +/- 10%, X7R, 0805	0805
12	C15	1	1000pF	C0805C102J5GACTU	Kemet	CAP, CERM, 1000 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
13	C16	1	0.1uF	C0805C104M5RACTU	Kemet	CAP, CERM, 0.1 μF, 50 V, +/- 20%, X7R, 0805	0805
14	C23	1	0.22uF	C0805C224K5RACTU	Kemet	CAP, CERM, 0.22 μF, 50 V, +/- 10%, X7R, 0805	0805
15	C26	1	220pF	08055A221JAT2A	AVX	CAP, CERM, 220 pF, 50 V, +/- 5%, C0G/NP0, 0805	0805
16	C27	1	0.1uF	C0603C104K8RACTU	Kemet	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X7R, 0603	0603
17	D1	1	20V	SL12-E3/61T	Vishay-Semiconductor	Diode, Schottky, 20 V, 1.5 A, SMA	SMA
18	D2, D3, D4, D5	4	30V	BAT54S-7-F	Diodes Inc.	Diode, Schottky, 30 V, 0.2 A, SOT-23	SOT-23
19	J1, J2	2		TSW-106-07-G-S	Samtec	Header, 100mil, 6x1, Gold, TH	6x1 Header
20	J3, J4, J5	3		TSW-104-07-G-S	Samtec	Header, 100mil, 4x1, Gold, TH	4x1 Header
21	J10	1		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
22	J11	1		TSW-103-07-G-D	Samtec	Header, 100mil, 3x2, Gold, TH	3x2 Header
23	L1	1	3.9uH	CDRH6D28NP-3R9NC	Sumida	Inductor, Shielded Drum Core, Ferrite, 3.9 µH, 2.6 A, 0.027 ohm, SMD	CDRH6D28
24	Q1	1	-12V	Si2335DS-T1-GE3	Vishay-Siliconix	MOSFET, P-CH, -12 V, -3.2 A, SOT-23	SOT-23
25	R1	1	430k	RG2012P-434-B-T5	Susumu Co Ltd	RES, 430 k, 0.1%, 0.125 W, 0805	0805
26	R2, R6	2	56.0k	RR1220P-563-D	Susumu Co Ltd	RES, 56.0 k, 0.5%, 0.1 W, 0805	0805
27	R3	1	620k	RG2012P-624-B-T5	Susumu Co Ltd	RES, 620 k, 0.1%, 0.125 W, 0805	0805
28	R4	1	150k	CRCW0805150KFKEA	Vishay-Dale	RES, 150 k, 1%, 0.125 W, 0805	0805
29	R5, R13	2	1.00Meg	RG2012P-105-B-T5	Susumu Co Ltd	RES, 1.00 M, 0.1%, 0.125 W, 0805	0805
30	R7	1	33.0k	RG2012P-333-B-T5	Susumu Co Ltd	RES, 33.0 k, 0.1%, 0.125 W, 0805	0805
31	R8, R9	2	510k	RR1220P-514-D	Susumu Co Ltd	RES, 510 k, 0.5%, 0.1 W, 0805	0805
32	R10, R12, R14,	4	0	MCR10EZHJ000	Rohm	RES, 0, 5%, 0.125 W, 0805	0805
	R15						
33	R11	1	100k	CRCW0805100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.125 W, 0805	0805
34	R26	1	5.6	CRCW08055R60JNEA	Vishay-Dale	RES, 5.6, 5%, 0.125 W, 0805	0805
35	SH-JP1, SH-JP2	2	1x2	969102-0000-DA	3M	Shunt, 100mil, Gold plated, Black	Shunt
36	U1	1		TPS65150PWP	Texas Instruments	3-Channel LCD Bias with GPM, VCOM Buffer & Gate Driver for Isolation	PWP0024B
						Switch, 1.8 to 6 V, -40 to 85 degC, 24-pin SOP (PWP24), Green (RoHS	
						& no Sb/Br)	
37	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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